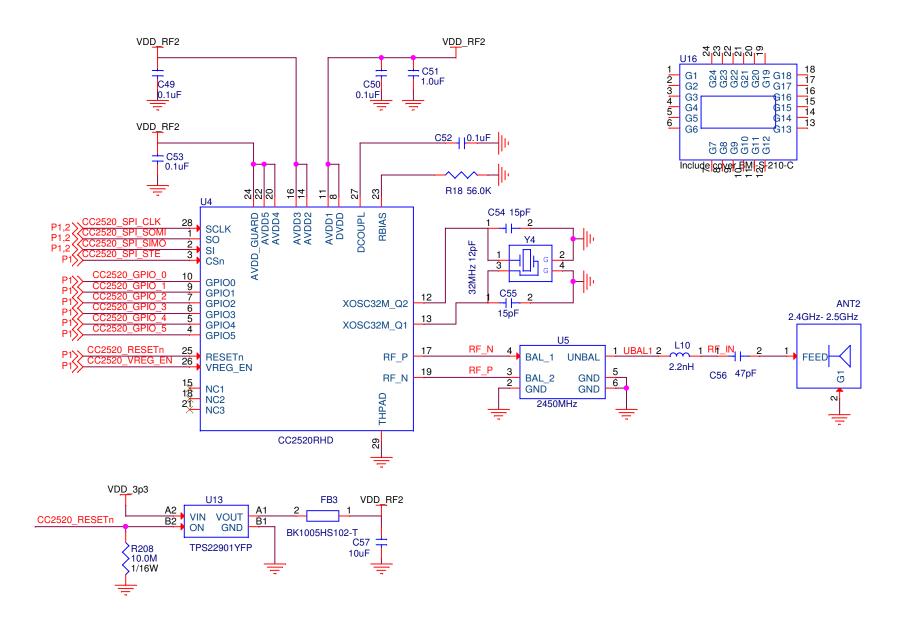


## SH2 - CC2520 (802.15.4 compatible radio)



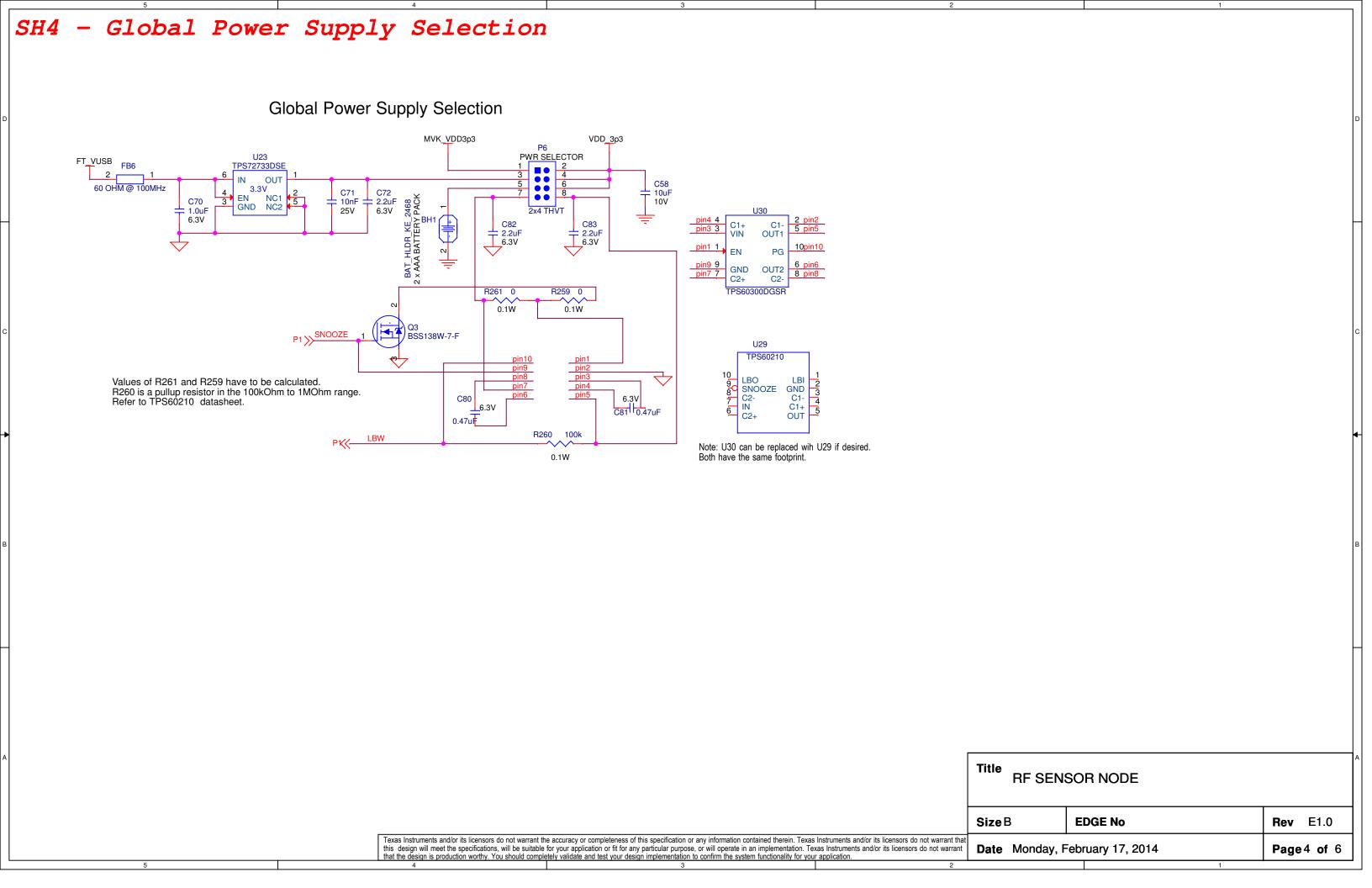
RF SENSOR NODE	Title	RF SENSOR NODE		
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Size B EDGE No Rev E1.0

Date Monday, February 17, 2014 Page 3 of 6

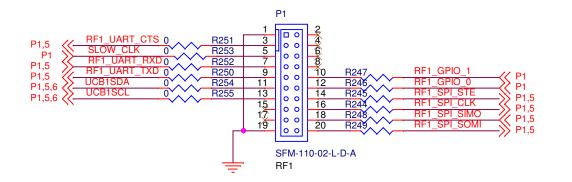
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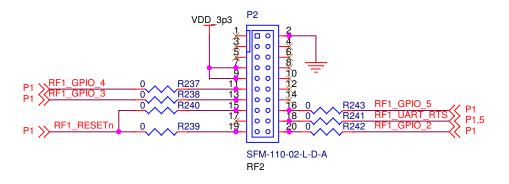
4 3 2



### SH5 - RF Connector Interface

RF card seen from TOP. (Connector Mounted on the BOTTOM) The connectors are spaced 1200mils center to center and are pushed all the way at the bottom on the card outline. Card is  $1500 \times 1200mils$ .





RF SENSOR NODE

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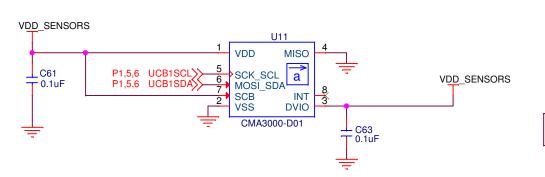
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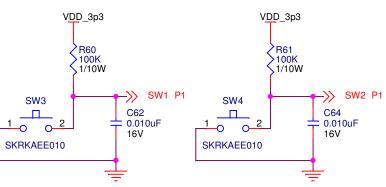
4 3 2

# SH6 - Sensors / External Flash / Keypad / LEDs

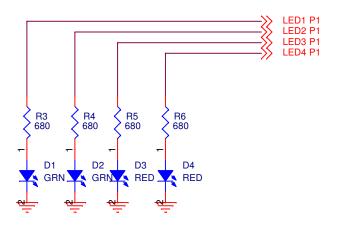
#### 3D ACCELLEROMETER



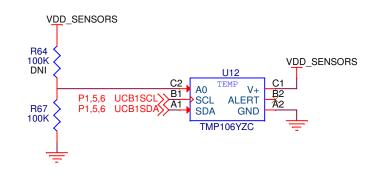
#### SIMPLE KEYPAD



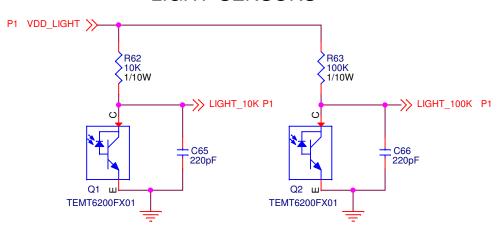
#### Indicator LED's



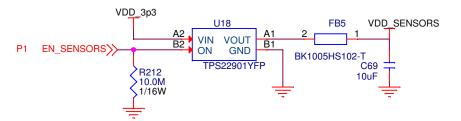
#### TEMPERATURE SENSOR



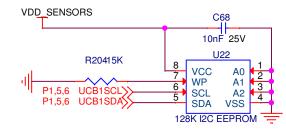
#### LIGHT SENSORS



#### LOCAL POWER ENABLE/DISABLE CIRCUIT



#### 12C EXTERNAL FLASH



### RF SENSOR NODE

	<b>Size</b> B	EDGE No	Rev	E1.0
that				

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4 3 2

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